

HANDLING INSTRUCTIONS MMIC

Göteborg Microwave Integrated Circuits

REV. A01-16

HANDLING RECOMMENDATIONS - BARE DIE PRODUCTS

The following handling recommendations must be considered in order to avoid damaging bare die products.

GENERAL HANDLING INSTRUCTIONS

The dies are fragile and must be handled using either a vacuum pickup tool or a pair of tweezers with soft tips. Tools and tweezers used for die handling must be clean. Only the edges of the die may be touched, as the top surface contains sensitive air-bridge structures.

STORAGE

The dies should be stored in GelPak-type containers.

CLEANLINESS

Bare dies must be handled in a clean environment to avoid contamination.

ELECTROSTATIC DISCHARGE

Standard ESD precautions must be followed at all times when handling bare die. Operators must wear ESD wrist wraps.

ELECTRICAL TESTING

Power supply and instrument transients should be avoided in order to prevent damage. All equipment should be connected with grounded AC power plugs and the system should be free from ground loops.

ASSEMBLY

Refer to the document "Assembly Instructions" found on Gotmic's website (<u>www.gotmic.se</u>) for more information.